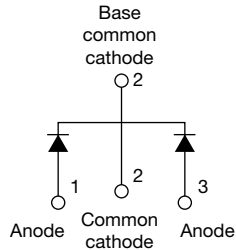


## Hyperfast Rectifier, 2 x 5 A FRED Pt<sup>®</sup>


**TO-252AA (D-PAK)**


### FEATURES

- Hyperfast recovery time
- 175 °C max. operating junction temperature
- Output rectification freewheeling
- Low forward voltage drop reduced  $Q_{rr}$  and soft recovery
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
 COMPLIANT  
 HALOGEN  
**FREE**

### PRODUCT SUMMARY

Package	TO-252AA (D-PAK)
$I_{F(AV)}$	2 x 5 A
$V_R$	200 V
$V_F$ at $I_F$	0.74 V
$t_{rr}$ (typ.)	23 ns
$T_J$ max.	175 °C
Diode variation	Common cathode

### DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		200	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 160\text{ °C}$	10	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$	80	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

### ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\ \mu\text{A}$	200	-	-	V
Forward voltage	$V_F$	$I_F = 5\text{ A}$	-	0.90	0.98	
		$I_F = 10\text{ A}$	-	0.98	1.15	
		$I_F = 5\text{ A}, T_J = 150\text{ °C}$	-	0.74	0.84	
Reverse leakage current per leg	$I_R$	$V_R = V_R$ rated	-	-	4	$\mu\text{A}$
		$T_J = 125\text{ °C}, V_R = V_R$ rated	-	-	40	
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	80	
Junction capacitance per leg	$C_T$	$V_R = 600\text{ V}$	-	17	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8	-	nH



DYNAMIC RECOVERY CHARACTERISTICS ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $dI_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$		-	23	27	ns
		$T_J = 25\text{ }^\circ\text{C}$	$I_F = 5\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	-	21	-	
		$T_J = 125\text{ }^\circ\text{C}$		-	26	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	$I_F = 5\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	-	2	-	A
		$T_J = 125\text{ }^\circ\text{C}$		-	3.1	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	$I_F = 5\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 160\text{ V}$	-	20	-	nC
		$T_J = 125\text{ }^\circ\text{C}$		-	41	-	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$			-65	-	175	$^\circ\text{C}$
Thermal resistance, $\frac{\text{per leg}}{\text{per device}}$	$R_{thJC}$			-	2.7	3.2	$^\circ\text{C}/\text{W}$
				-	1.35	1.6	
Approximate weight					0.3		g
					0.01		oz.
Marking device			Case style TO-252AA (D-PAK)	10CWH02FN			

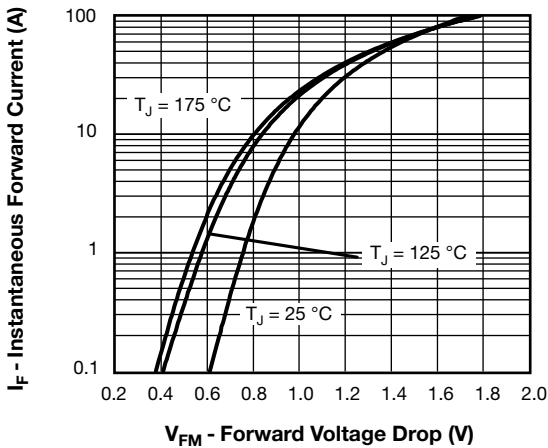


Fig. 1 - Typical Forward Voltage Drop Characteristics

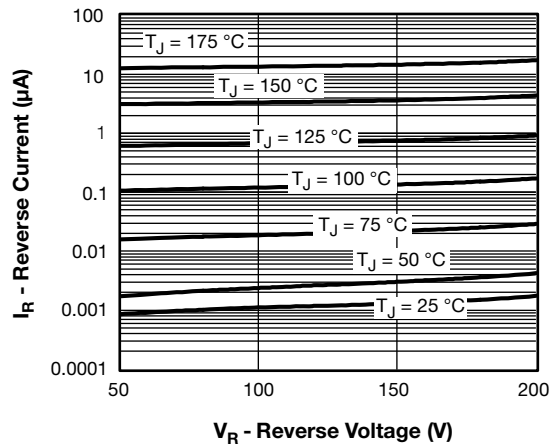


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

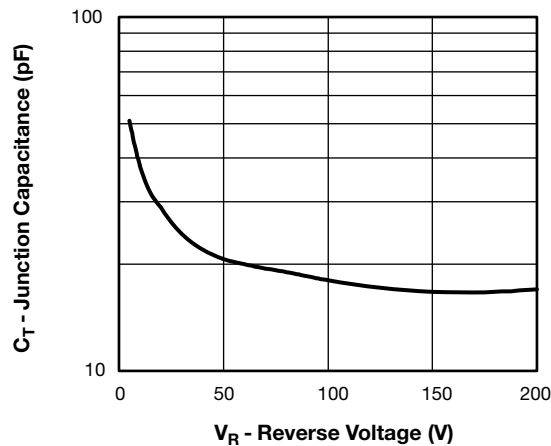


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

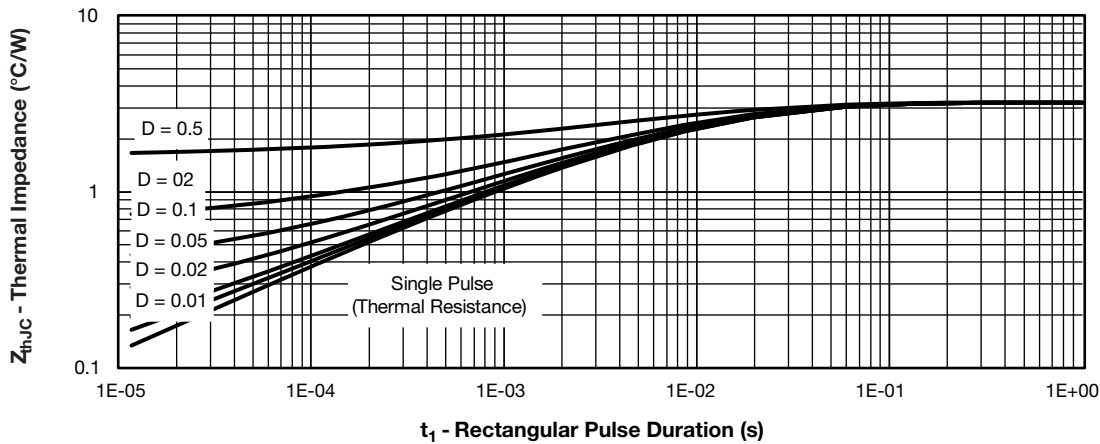


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

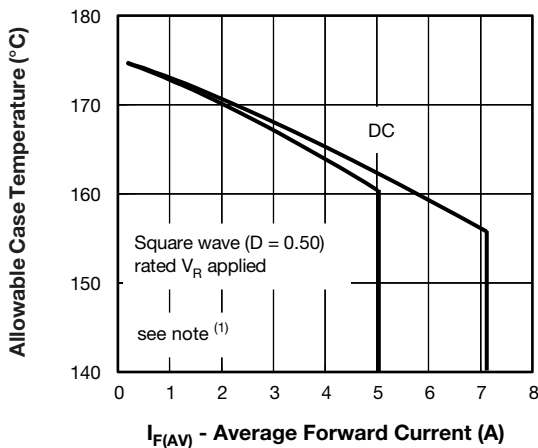


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

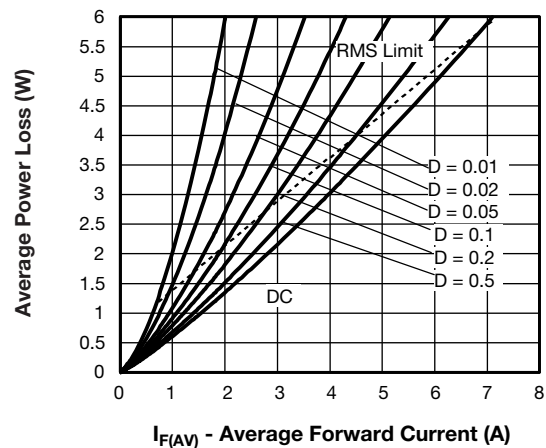


Fig. 6 - Forward Power Loss Characteristics

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;
- $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

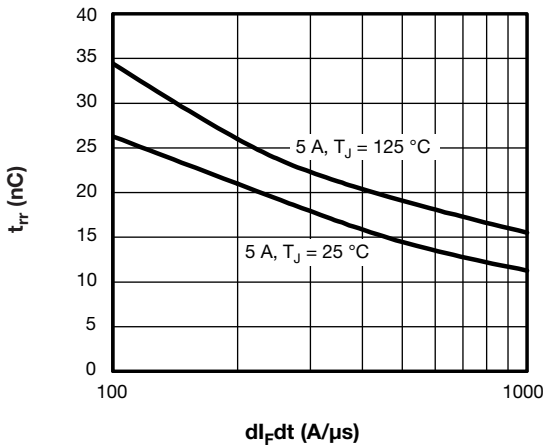


Fig. 7 - Typical Reverse Recovery Time vs.  $di/dt$

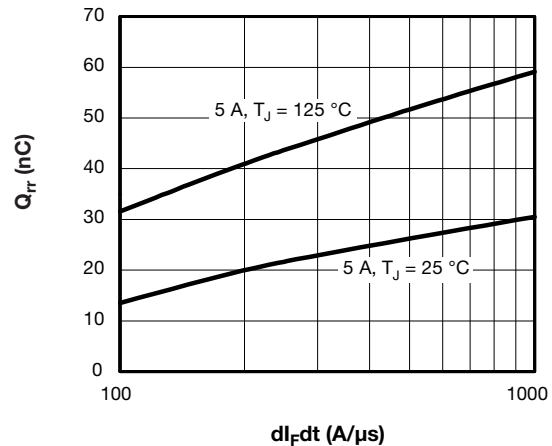


Fig. 8 - Typical Stored Charge vs.  $di/dt$

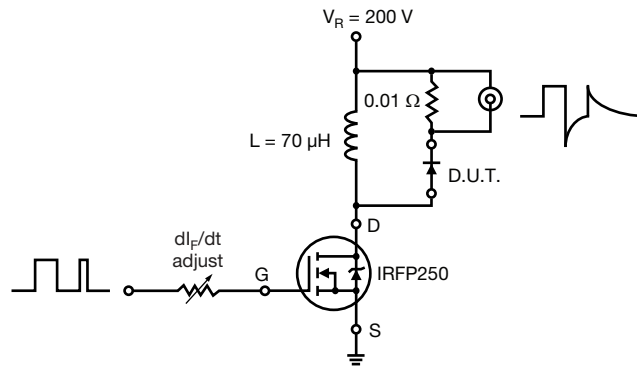
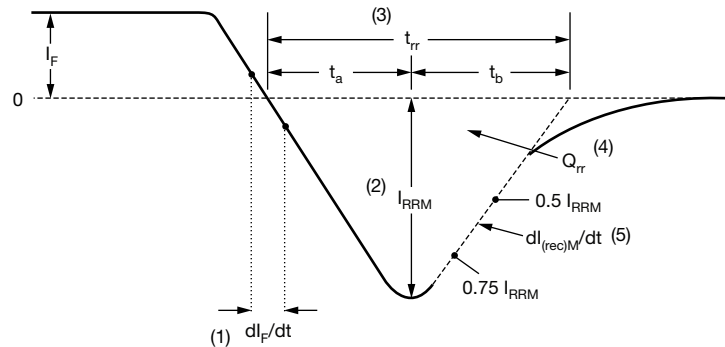


Fig. 9 - Reverse Recovery Parameter Test Circuit



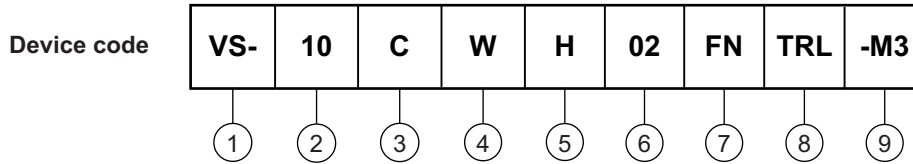
- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $dl_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (10 = 10 A)
- 3** - Circuit configuration:  
C = common cathode
- 4** - Package identifier:  
W = D-PAK
- 5** - H = hyperfast recovery
- 6** - Voltage rating (02 = 200 V)
- 7** - FN = TO-252AA
- 8** -
  - None = tube
  - TR = tape and reel
  - TRL = tape and reel (left oriented)
  - TRR = tape and reel (right oriented)
- 9** - Environmental digit:  
-M3 = halogen-free, RoHS-compliant and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10CWH02FN-M3	75	3000	Antistatic plastic tube
VS-10CWH02FNTR-M3	2000	2000	13" diameter reel
VS-10CWH02FNTRL-M3	3000	3000	13" diameter reel
VS-10CWH02FNTRR-M3	3000	3000	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95627">www.vishay.com/doc?95627</a>
Part marking information	<a href="http://www.vishay.com/doc?95176">www.vishay.com/doc?95176</a>
Packaging information	<a href="http://www.vishay.com/doc?95033">www.vishay.com/doc?95033</a>
SPIICE model	<a href="http://www.vishay.com/doc?95376">www.vishay.com/doc?95376</a>

### D-PAK (TO-252AA) "M"

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094		e	2.29 BSC		0.090 BSC		
A1	-	0.13	-	0.005		H	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035		L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045		L1	2.74 BSC		0.108 REF.		
b3	4.95	5.46	0.195	0.215	3	L2	0.51 BSC		0.020 BSC		
c	0.46	0.61	0.018	0.024		L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035		L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5	L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3	Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3	Ø2	25°	35°	25°	35°	

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA



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